

<b>PART INFORMATION</b>	
Mfg Item Number	MPX5999D
Mfg Item Name	6 PIN UNIBODY
<b>SUPPLIER</b>	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2013-06-19
Response Document ID	0730K50010S197A1.26
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com
<b>DECLARATION</b>	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	No
Plating Indicator	e4
EU RoHS Exemption(s)	
<b>MANUFACTURING</b>	
Mfg Item Number	MPX5999D
Mfg Item Name	6 PIN UNIBODY
Version	ALL
Weight	1.865050
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.</p>
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

## MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Cap/Cover	0.2853		Metals	Chromium, metal	7440-47-3	0.048346	g	169458	16.9458	25922	2.5922
Cap/Cover		Metals	Sulfur	7704-34-9	0.000085	g	299	0.0299	45	0.0045	
Cap/Cover		Solvents, additives, and other materials	Phosphorus	7723-14-0	0.000114	g	399	0.0399	61	0.0061	
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3	0.002133	g	7476	0.7476	1143	0.1143	
Cap/Cover		Metals	Iron, metal	7439-89-6	0.23178	g	812400	81.24	124276	12.4276	
Cap/Cover		Metals	Manganese, metal	7439-96-5	0.002844	g	9968	0.9968	1524	0.1524	
Die Encapsulant	1.01505						g			13110	1.311
Die Encapsulant		Flame Retardants	Antimony trioxide	1309-64-4	0.024451	g	24088	2.4088	17479	1.7479	
Die Encapsulant		Flame Retardants	Bromophenol, formaldehyde, epichlorohydrin polymer	68541-56-0	0.0326	g	32117	3.2117	87398	8.7398	
Die Encapsulant		Plastics/polymers	Formaldehyde, polymer with 2-methylphenol, glycidyl ether	64425-89-4	0.163001	g	166584	16.0564	51346	5.1346	
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.002802	g	2750	0.276	371451	37.1451	
Die Encapsulant		Metals	Lead, metallic lead and lead alloys	7439-92-1	0.000013	g	13	0.0013	6	0.0006	
Die Encapsulant		Solvents, additives, and other materials	(3,4-Epoxy)cyclohexylmethylnethoxysilane	3388-04-3	0.003667	g	3613	0.3613	1966	0.1966	
Die Encapsulant		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4	0.095763	g	94343	9.4343	51346	5.1346	
Die Encapsulant		Glass	Silica, vitreous	60676-86-0	0.692753	g	682482	68.2482			
Non-Conductive Epoxy/Adhesive	0.0078						g			43	0.0043
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-94-1	0.000081	g	10324	1.0324	514	0.0514	
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1	0.000059	g	122911	12.2911	1644	0.1644	
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2	0.030367	g	393313	39.3313	925	0.0925	
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-	0.00126	g	221239	22.1239	616	0.0616	
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9	0.00115	g	147493	14.7493	390	0.039	
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7	0.000729	g	93412	9.3412	47	0.0047	
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7	0.000088	g	11308	1.1308	636	0.0536	
Bonding Wire	0.001						g			80588	8.0588
Gel Die Encapsulant	0.1503						g				
Gel Die Encapsulant		Solvents, additives, and other materials	Proprietary Material-Other inorganic fluorine compounds and their aqueous salts	-	0.1503	g	1000000	100			
Copper Lead Frame	0.3176						g			164861	16.4861
Copper Lead Frame		Metals	Copper, metal	7440-50-8	0.307472	g	968112	96.8112	17	0.0017	
Copper Lead Frame		Metals	Gold, metal	7440-57-5	0.000032	g	100	0.01	3715	0.3715	
Copper Lead Frame		Metals	Iron, metal	7439-89-6	0.00693	g	21820	2.182	2	0.0002	
Copper Lead Frame		Metals	Lead, metallic lead and lead alloys	7439-92-1	0.000005	g	16	0.0016	1426	0.1426	
Copper Lead Frame		Metals	Nickel, metal	7440-02-0	0.002661	g	8377	0.8377	72	0.0072	
Copper Lead Frame		Metals	Palladium, metal	7440-05-3	0.000135	g	426	0.0426	195	0.0195	
Copper Lead Frame		Metals	Zinc, metal	7440-66-6	0.000365	g	1149	0.1149			
Bonding Agent	0.0415						g			100113	1.0013
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-	0.018675	g	450000	45	556	0.0556	
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-	0.001038	g	25000	2.5	556	0.0556	
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.001038	g	25000	2.5	11125	1.1125	
Bonding Agent		Plastics/polymers	Other phenolic resins	-	0.020749	g	500000	50			
Bonding Agent	0.0415						g			100113	1.0013
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-	0.018675	g	450000	45	556	0.0556	
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-	0.001038	g	25000	2.5	556	0.0556	
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.001038	g	25000	2.5	11125	1.1125	
Bonding Agent		Plastics/polymers	Other phenolic resins	-	0.020749	g	500000	50			
Silicon Semiconductor Die	0.005						g			53	0.0053
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-	0.0001	g	20000	2	2627	0.2627	
Silicon Semiconductor Die		Glass	Silicon, doped	-	0.0049	g	980000	98			

**LINKS**

MCD LINK

Freescale website <http://www.freescale.com>**GENERAL ENVIRONMENTAL COMPLIANCE LINKS**RoHS signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_ROHS\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf)China RoHS <http://www.freescale.com/chinarohs>REACH signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_REACH\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf)ELV signed letter [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_ELV\\_Freescale\\_Reponse.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf)Conflict Minerals statement [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/ENV\\_CONFLICT\\_METAL\\_Freescale\\_Response.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf)**FREESCALE ENVIRONMENTAL INFORMATION**EPP website <http://www.freescale.com/epp>FAQ [http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON\\_FAQ](http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ)Technical Service Request [https://www.freescale.com/webapp/servicerequest.create\\_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod](https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod)**LINKS TO BLANK IPC1752 FORMS**Blank IPC1752 v0.9 Form [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/IPC-1752-2\\_v0.9\\_MCD\\_Template.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf)Blank IPC1752 v1.1 Form [http://www.freescale.com/files/abstract/corporate/ehs\\_epp/IPC-1752-2\\_v1.1\\_MCD\\_Template.pdf](http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf)

IPC1752 XML LINKS

[http://www.freescale.com/mcds/MPX5999D\\_IPC1752\\_v09.xml](http://www.freescale.com/mcds/MPX5999D_IPC1752_v09.xml)

[http://www.freescale.com/mcds/MPX5999D\\_IPC1752\\_v11.xml](http://www.freescale.com/mcds/MPX5999D_IPC1752_v11.xml)

[http://www.freescale.com/mcds/MPX5999D\\_IPC1752A.xml](http://www.freescale.com/mcds/MPX5999D_IPC1752A.xml)